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US 5263245 A	19931123	Method of making an electronic package with enhanced heat sinking	29/840	Patel, Maganlal S. et al.
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1	8856	printed adj circuit adj board and multi\$1layer	USPAT; EPO; JPO	2004/02/18 12:06
2	386	(printed adj circuit adj board and multi\$1layer) and signal adj (plane layer) and (ground power reference) adj (plane layer)	USPAT; EPO; JPO	2004/02/18 12:07
3	22	("3739469" "4170819" "4211603" "4675788" "4679872" "5057809" "5225969" "5374788" "5376759" "5421083" "5459642" "5565262" "5612660" "5808529" "5823795" "5847451" "5853303" "5876842" "5921815" "5949030" "6019639" "6228511").PN.	USPAT	2004/02/18 12:09
4	7	("5006820" "5281151" "5451721" "5686764" "6194668" "6271478" "6335493").PN.	USPAT	2004/02/18 12:13
5	7	("5363280" "5371653" "5451720" "5473813" "5590030" "5743004" "6080012").PN.	USPAT	2004/02/18 12:14
6	6	5743004.URPN.	USPAT	2004/02/18 12:15
7	3	("5281151" "5451721" "5686764").PN.	USPAT	2004/02/18 12:18
8	29	4511950.URPN.	USPAT	2004/02/18 12:31
9	13	("4328530" "4450029" "4511950" "4575745" "4616292" "4628411" "4647877" "4694123" "5102352" "5136471" "5418690" "5451720" "5523921").PN.	USPAT	2004/02/18 12:32
12	10	5930119.URPN.	USPAT	2004/02/18 14:09
13	9	("4362899" "4738632" "4879433" "5365406" "5509066" "5541369" "5568361" "5696667" "5764489").PN.	USPAT	2004/02/18 14:10
16	24	4675789.URPN.	USPAT	2004/02/18 14:14
17	6	("3519959" "3568000" "3680005" "3740678" "4362899" "4498122").PN.	USPAT	2004/02/18 14:18
20	27	3740678.URPN.	USPAT	2004/02/18 14:27
21	932	174/\$.ccls. and dielectric and (signal ground power) adj (plane layer core)	USPAT; EPO; JPO	2004/02/18 16:49
22	211	(174/\$.ccls. and dielectric and (signal ground power) adj (plane layer core)) and laminat\$4 and copper with thick\$4	USPAT; EPO; JPO	2004/02/18 16:39
23	49	257/7\$.ccls. and dielectric and (signal ground power) adj (plane layer core) and lamination and (copper cu) with thickness	USPAT; EPO; JPO	2004/02/18 16:51
24	79	361/7\$.ccls. and dielectric and (signal ground power) adj (plane layer core) and lamination and (copper cu) with thickness	USPAT; EPO; JPO	2004/02/18 16:53
25	43	438/\$.ccls. and dielectric and (signal ground power) adj (plane layer core) and lamination and (copper cu) with thickness	USPAT; EPO; JPO	2004/02/18 16:54
26	13	333/\$.ccls. and dielectric and (signal ground power) adj (plane layer core) and lamination and (copper cu) with thickness	USPAT; EPO; JPO	2004/02/18 16:55
-	6	backplane.ti. and goergen.in.	USPAT; US-PGPUB; EPO; JPO	2004/02/09 18:56
-	673	multi\$1layer adj circuit with board and laminat\$3 and through adj hole	USPAT; EPO; JPO	2004/02/09 18:57
-	83	(multi\$1layer adj circuit with board and laminat\$3 and through adj hole) and (copper power signal) adj layer same dielectric	USPAT; EPO; JPO	2004/02/09 18:58

-	1	5311406.pn.	USPAT; EPO; JPO	2004/02/09 19:00
-	64	29/\$.ccls. and multi\$1layer with (substrate board) and (dielectric insulat\$3) adj layer and laminat\$4 and power adj (plane layer)	USPAT; EPO; JPO	2004/02/13 15:45
-	13	(backplane back\$1plane) and multi\$1layer with (substrate board) and (dielectric insulat\$3) adj layer and laminat\$4 and power adj (plane layer)	USPAT; EPO; JPO	2004/02/13 15:48
-	124	stack\$3 and multi\$1layer with (substrate board) and (dielectric insulat\$3) adj layer and laminat\$4 and power adj (plane layer)	USPAT; EPO; JPO	2004/02/13 15:58
-	299	circuit adj board and stack\$3 and multi\$1layer with (substrate board) and (dielectric insulat\$3) adj (film layer plane material) and laminat\$4 and (ground power) adj (plane layer film)	USPAT; EPO; JPO	2004/02/13 16:17
-	268	circuit adj board and stack\$3 and multi\$1layer with (substrate board) and (dielectric insulat\$3) adj (film layer plane material) and laminat\$4 and (ground power signal) adj (plane layer film) and copper	USPAT; EPO; JPO	2004/02/13 16:19
-	26	three with (ounce oz) with copper with (layer film plane)	USPAT; EPO; JPO	2004/02/13 16:51
-	1	4891616.pn.	USPAT; EPO; JPO	2004/02/17 11:47
-	1	6081340.pn.	USPAT; EPO; JPO	2004/02/17 11:48
-	1	5010641.pn.	USPAT; EPO; JPO	2004/02/17 11:48
-	1	5870274.pn.	USPAT; EPO; JPO	2004/02/17 11:49
-	1	5566083.pn.	USPAT; EPO; JPO	2004/02/17 11:49
-	1	5261153.pn.	USPAT; EPO; JPO	2004/02/17 11:50
-	1	4694123.pn.	USPAT; EPO; JPO	2004/02/17 11:50
-	1	6030693.pn.	USPAT; EPO; JPO	2004/02/17 11:50
-	1	5311406.pn.	USPAT; EPO; JPO	2004/02/17 11:51
-	1	6229095.pn.	USPAT; EPO; JPO	2004/02/17 11:51
-	1	5397861.pn.	USPAT; EPO; JPO	2004/02/17 11:52
-	1	6015300.pn.	USPAT; EPO; JPO	2004/02/17 11:52
-	1	5841074.pn.	USPAT; EPO; JPO	2004/02/17 11:53
-	1	4862161.pn.	USPAT; EPO; JPO	2004/02/17 11:53
-	1	5548734.pn.	USPAT; EPO; JPO	2004/02/17 11:53
-	1	5308926.pn.	USPAT; EPO; JPO	2004/02/17 11:54
-	1	5682298.pn.	USPAT; EPO; JPO	2004/02/17 11:54
-	1	6091609.pn.	USPAT; EPO; JPO	2004/02/17 11:55
-	1	6181004.pn.	USPAT; EPO; JPO	2004/02/17 11:55
-	1	6333981.pn.	USPAT; EPO; JPO	2004/02/17 12:06
-	1	6573600.pn.	USPAT; EPO; JPO	2004/02/17 12:06
-	2	5841074.URPN.	USPAT	2004/02/17 14:32

-	13	("4328530" "4450029" "4511950" "4575745" "4616292" "4628411" "4647877" "4694123" "5102352" "5136471" "5418690" "5451720" "5523921").PN.	USPAT	2004/02/17 14:32
-	6	6181004.URPN.	USPAT	2004/02/17 14:34
-	70	("4100377" "4645872" "4771425" "4802199" "4843606" "4866704" "4886704" "4896350" "4964159" "4969184" "5068888" "5159592" "5185502" "5208806" "5208811" "5212691" "5309437" "5327486" "5333188" "5341374" "5343517" "5375118" "5400068" "5406557" "5406620" "5428608" "5430727" "5432848" "5432907" "5438565" "5440554" "5444477" "5457684" "5463625" "5469504" "5473680" "5479487" "5481600" "5491693" "5511114" "5519704" "5521914" "5526353" "5533018" "5541917" "5541927" "5553063" "5561670" "5563937" "5572643" "5583920" "5590181" "5604737" "5608446" "5608786" "5610910" "5636216" "5646982" "5712907" "5724355" "5742596" "5742670" "5790548" "5867495" "5889774" "5894512" "6103135" "6131279" "6181004" "6255039").PN.	USPAT	2004/02/17 14:40
-	1180	multi\$llayer with circuit adj board and (ground signal power) adj (plane layer film)	USPAT; EPO; JPO	2004/02/17 18:05
-	463	(multi\$llayer with circuit adj board and (ground signal power) adj (plane layer film)) and dielectric and laminat\$3	USPAT; EPO; JPO	2004/02/17 18:06
-	395	((multi\$llayer with circuit adj board and (ground signal power) adj (plane layer film)) and dielectric and laminat\$3) and copper	USPAT; EPO; JPO	2004/02/17 18:06
-	20	((multi\$llayer with circuit adj board and (ground signal power) adj (plane layer film)) and dielectric and laminat\$3) and copper) and (polyphenylene FR-4 adj1 resin)	USPAT; EPO; JPO	2004/02/17 18:07
-	233	((multi\$llayer with circuit adj board and (ground signal power) adj (plane layer film)) and dielectric and laminat\$3) and copper) and (polyphenylene resin)	USPAT; EPO; JPO	2004/02/17 18:09

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Gisin, F.; Pantic-Tanner, Z.;

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2 Wiring statistics and printed wiring board thermal conductivity

Nelson, R.D.;

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3 Ground starvation effects on multi-layer PCBs

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4 Investigation of the effectiveness of DC power bus interplane capacitance in reducing radiated EMI from multi-layer PCBs

O'Sullivan, C.B.; Musladin, M.;

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5 Multichip Packaging Design for VLSI-Based Systems

Bartlett, C.; Segelken, J.; Teneketges, N.;

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6 Simplified modeling of parallel plate resonances on multilayer printed circuit boards

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9 Simultaneous switching noise suppression for high speed systems using embedded decoupling

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10 Composite effects of reflections and ground bounce for signal vias in multi-layer environment

Sheng-Mou Lin; Ruey-Beei Wu;

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Wei Cui; Xiaoning Ye; Archambeault, B.; White, D.; Min Li; Drewniak, J.L.;

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12 Escape routing from chip scale packages

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13 Thermal evaluation of Θ_{JA} for varying board conductivity

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